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Bib Data Sheet

**CONFIRMATION NO. 9522** 

| SERIAL NUMBE<br>10/520,141   | FILING OR 371(c) DATE 09/01/2005 RULE   | <b>CLASS</b><br>438    | GROUP ART<br>2812      | OUP ART UNIT<br>2812   |  | ATTORNEY<br>DOCKET NO.<br>122261 |  |
|--|---|------------------------|------------------------|--|--|----------------------------------|--|
| APPLICANTS Shigehiro Nishino, Kyoto, JAPAN; Kazutoshi Murata, Okayama, JAPAN;  ** CONTINUING DATA ********************* This application is a 371 of PCT/JP03/08312 06/30/2003  ** FOREIGN APPLICATIONS ************************************ |   |                        |                        |  |  |                                  |  |
| Foreign Priority claimed<br>35 USC 119 (a-d) cond<br>met<br>Verified and<br>Acknowledged<br>ADDRESS<br>25944   | litions yes no Met a  | state or country JAPAN | SHEETS<br>DRAWING<br>3 | TOTAL<br>CLAIMS<br>5   |  | INDEPENDENT<br>CLAIMS<br>2       |  |
| TITLE  Large-diameter sic wafer and manufacturing method thereof   |   |                        |                        |  |  |                                  |  |
| RECEIVED N   | FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: |                        |                        | ☐ All Fees ☐ 1.16 Fees (Filing) ☐ 1.17 Fees (Processing Ext. of time) ☐ 1.18 Fees (Issue) ☐ Other ☐ Credit |  |                                  |  |